

9200 NVMe™ SSDs

**MTFDHAL1T6TCU, MTFDHAL1T9TCT, MTFDHAL3T2TCU,
MTFDHAL3T8TCT, MTFDHAL6T4TCU, MTFDHAL7T6TCT,
MTFDHAL8TATCW, MTFDHAL11TATCW**

Features

- Micron® 3D NAND Flash
- PCI Express® (PCIe®) Gen3 ×4
- NVM Express™ (NVMe™) Specification 1.2
- Capacity¹
 - 9200 ECO: 8.0TB, 11.0TB
 - 9200 PRO: 1.92TB, 3.84TB, 7.68TB
 - 9200 MAX: 1.6TB, 3.2TB, 6.4TB
- Endurance (total bytes written)¹
 - 1.6TB: Up to 17.5PB
 - 1.92TB: Up to 16.8PB
 - 3.2TB: Up to 29.8PB
 - 3.84TB: Up to 29.4PB
 - 6.4TB: Up to 59.5PB
 - 7.68TB: Up to 58.8PB
 - 8.0TB: Up to 58.4PB
 - 11.0TB: Up to 80.3PB
- Industry-standard 512-byte and 4096-byte sector size support
- Power: <8W idle, 25W power limited, or unlimited
- Surprise insertion/surprise removal (SISR) and hot-plug capable
- Power-backed cache
- Steady state performance^{1, 2} (varies by capacity and form factor)
 - Sequential 128KB read: Up to 3.50 GB/s
 - Sequential 128KB write: Up to 3.50 GB/s
 - Random 4KB read: Up to 840K IOPS
 - Random 4KB write: Up to 285K IOPS
- Latency to media performance, typical (QD = 1)
 - READ: 92–150µs³
 - WRITE: 21µs
- Reliability
 - MTTF: 2 million hours⁴
 - Field-upgradable firmware
 - UBER: <1 sector per 10¹⁷ bits read
- SMBus out-of-band management
- End-to-end data path protection
- SMART command set support
- Cryptographic erase⁵
- FlexPro (flexible over provisioning)

- Zero Return After TRIM (ZRAT)⁶
- Temperature⁷
 - 0°C to 85°C SMART temperature
 - 0°C to 35°C ambient
 - Temperature protection
- Mechanical/electrical
 - U.2: 69.85 × 15.00 × 100.5mm, 12V (–6%/+8%)
- Shock: 1500g @ 0.5ms
- Vibration: 3.1 G_{RMS} 5–800Hz @ 30 min/axis

Controller Features

- NVMe controller
 - Number of queues: 128 SQ/CQ pairs
 - Round robin arbitration: not weighted
- Interrupt coalescing
- NVMe command set attributes
 - Completion queue entry size: 16 bytes
 - Submission queue entry size: 64 bytes
- 4KB Atomic operations

- Notes:
1. User capacity: 1GB = 1 billion bytes;
1TB = 1 trillion bytes;
1PB = 1 peta bytes.
 2. Steady state as defined by SNIA Solid State Storage Performance Test Specification Enterprise v1.1.
 3. READ latency varies by capacity.
 4. Based on population statistics that are not relevant to individual units and a T_{CASE} of 60°C.
 5. 4K sector size support only.
 6. 4K aligned data only.
 7. Operating temperature is the drive case temperature as measured by the SMART temperature. See air flow recommendations.

Native Drivers

- Microsoft Windows Server® 2016
- Red Hat® Enterprise Linux (RHEL) 6.5+
- CentOS® 6.5+
- SUSE® Linux Enterprise Server 11 SP4, 12+
- Ubuntu® 12.04.03+, 14.04+
- VMware® 5.5, 6.0+

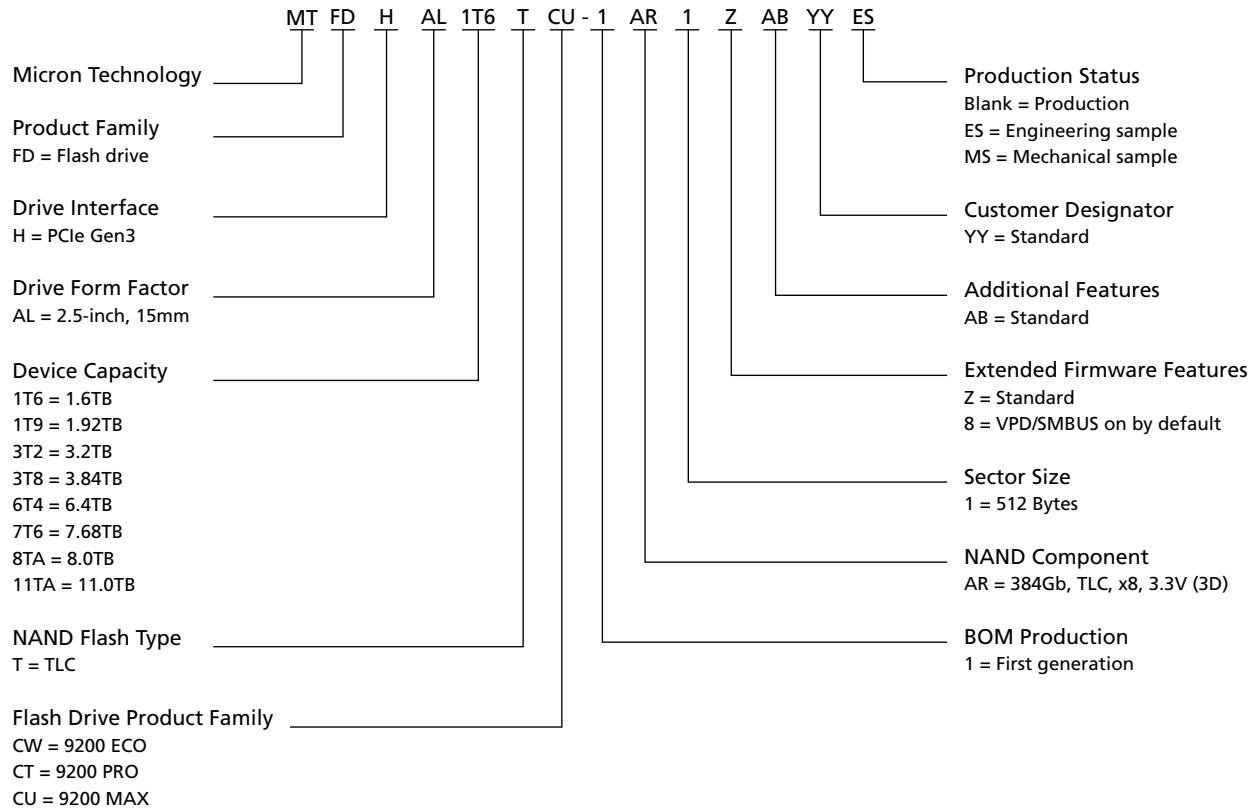
Custom Drivers

- Microsoft Windows Server 2012 R2, Hyper-V (recommended)
- RHEL 6.1-6.4
- CentOS 6.1-6.4
- SUSE Linux Enterprise Server 11 SP1-SP3

Part Numbering Information

The Micron 9200 SSD is available in different configurations and capacities. Visit www.micron.com for a list of valid part numbers.

Figure 1: Part Number Chart



Warranty: Contact your Micron sales representative for further information regarding the product, including product warranties.

General Description

The Micron 9200 NVMe SSD Series is Micron's flagship performance product line. These products utilize a Gen3 PCIe interface, the innovative Non-Volatile Memory Express protocol and Micron's own high-speed NAND to provide high throughput and IOPS, very low latency, and consistent quality of service. The 9200 product line has Micron's FlexPro™ firmware architecture which allows you to actively tune capacity to optimize drive performance and endurance and is available in high capacities up to 11 TBs. Reliability assurance measures include cyclic redundancy checks (CRC), end-to-end data path protection, capacitor-backed power loss protection and Micron's extensive validation, quality and reliability testing. It features thermal monitoring and protection, SMART attributes for status polling and SMBus for out-of-band management.

The Micron 9200 has three endurance classes: the PRO for read-centric use at roughly 1 drive writes per day (DWPD); the MAX for mixed-use workloads at about 3 DWPD; and the ECO for less than 1 DWPD. The PRO version comes in 1.92TB, 3.84TB, and 7.68TB capacities, while the MAX is sized at 1.6TB, 3.2TB, 6.4TB, and the ECO in 8.0TB and 11.0TB.

Logical Block Address Configuration

The drive is set to report the number of logical block addresses (LBA) that will ensure sufficient storage space for the specified capacity. Standard LBA settings, based on the IDEMA standard (LBA1-03), are shown below.

Table 1: Standard LBA Settings

| Capacity | 512-Byte Sector LBA Count | 4096-Byte Sector LBA Count |
|----------|---------------------------|----------------------------|
| 1.6TB | 3,125,627,568 | 390,703,446 |
| 1.92TB | 3,750,748,848 | 468,843,606 |
| 3.2TB | 6,251,233,968 | 781,404,246 |
| 3.84TB | 7,501,476,528 | 937,684,566 |
| 6.4TB | 12,502,446,768 | 1,562,805,846 |
| 7.68TB | 15,002,931,888 | 1,875,366,486 |
| 8.0TB | 15,628,053,168 | 1,953,506,646 |
| 11.0TB | 21,488,565,168 | 2,686,070,646 |

Performance

Table 2: Drive Performance

| Specification | 9200 ECO (TB) | | 9200 PRO (TB) | | | 9200 MAX (TB) | | | Unit |
|--|------------------|------|------------------|------|------|------------------|------|------|------|
| | 8.0 | 11.0 | 1.92 | 3.84 | 7.68 | 1.6 | 3.2 | 6.4 | |
| Sequential read (128KB I/O size) | 3.50 | 3.50 | 3.50 | 3.50 | 3.50 | 3.50 | 3.50 | 3.50 | GB/s |
| Sequential write (128KB I/O size) | 3.10 | 3.50 | 1.90 | 3.10 | 3.10 | 1.90 | 3.10 | 3.10 | |
| Random read (4KB I/O size) | 840K | 840K | 680K | 840K | 840K | 680K | 840K | 840K | IOPS |
| Random write (4KB I/O size) | 140K | 130K | 185K | 170K | 170K | 255K | 285K | 280K | |
| Mixed 70/30 read/write (4KB I/O size) | 320K | 335K | 305K | 360K | 360K | 370K | 500K | 465K | |

- Notes:
1. Performance specifications shown are with power limiting off. See Electrical Characteristics section for more details.
 2. Performance is steady state as defined by SNIA Solid State Storage Performance Test Specification Enterprise v1.1.
 3. Performance may vary up to 10% over life of drive.

Table 3: Latency

| Specification | Queue Depth = 1 | Unit |
|------------------------------------|-----------------|------|
| READ latency (TYP) 1.6TB–3.84TB | 92 | μs |
| READ latency (TYP) 6.4TB–8TB | 101 | |
| READ latency (TYP) 11TB | 105 | |
| WRITE latency (TYP) all capacities | 21 | |

- Note: 1. Quality of service is measured using random 4KB workloads, QD = 1 at steady state.

Functional Description

Mean Time to Failure

The mean time to failure (MTTF) for the device can be calculated based on the component reliability data using the methods referenced in the Telcordia SR-322 reliability prediction procedures for electronic equipment and measured during reliability demonstration test.

Table 4: MTTF

| Capacity | MTTF (Operating Hours) |
|----------|------------------------|
| All | 2.0 million |

Endurance

SSD endurance is dependent on many factors, including: usage conditions applied to the drive, drive performance and capacity, formatted sector size, error correction codes (ECCs) in use, internal NAND PROGRAM/ERASE cycles, write amplification factor, wear-leveling efficiency of the drive, over-provisioning ratio, valid user data on the drive, drive temperature, NAND process parameters, and data retention time.

The device is designed to operate under a wide variety of conditions, while delivering the maximum performance possible and meeting enterprise market demands.

While actual endurance varies depending on conditions, the drive lifetime can be estimated based on capacity, assumed fixed-use models, ECC, and formatted sector size. Lifetime estimates for the device are shown in the following tables in total bytes written.

Table 5: Total Bytes Written

| Model | Capacity (TB) | 4K Random Total Bytes Written (PB) | 128K Sequential Total Bytes Written (PB) |
|----------|---------------|---------------------------------------|---|
| 9200 ECO | 8.0 | 11.7 | 58.4 |
| | 11.0 | 16.1 | 80.3 |
| 9200 PRO | 1.92 | 3.5 | 16.8 |
| | 3.84 | 7.0 | 29.4 |
| | 7.68 | 14.0 | 58.8 |
| 9200 MAX | 1.6 | 8.8 | 17.5 |
| | 3.2 | 17.5 | 29.8 |
| | 6.4 | 35.1 | 59.5 |

- Notes:
1. Values shown are based on system modeling.
 2. Values represent the theoretical minimum and maximum endurance. Actual lifetime will vary by workload. Refer to the "Percentage used" in the SMART/health log to check the device life used (and remaining).

Data Retention

Data retention refers to the capability of the SSD media (that is, NAND flash) to retain programmed data. The three primary factors that affect data retention are:

- Power-on/power-off state: Data retention generally improves when the SSD is in use (that is, not shelved in a power-off state).
- Temperature: Data retention decreases as the temperature increases.
- Number of PROGRAM/ERASE cycles on the media: When the SSD ships from the factory, it is typically able to retain user data for up to 5 years in a powered-off state.

Data retention is guaranteed for three months at 40°C (MAX), which assumes worst-case power and media wear (the SSD remains in a powered-off state and has reached end of life).

Wear Leveling

The device uses sophisticated wear-leveling algorithms to maximize endurance by distributing PROGRAM/ERASE cycles uniformly across all blocks in the array. Both static and dynamic wear leveling are utilized to optimize the drive's lifespan.

Both types of wear leveling aim to distribute “hot” data away from blocks that have experienced relatively heavy wear. Static wear leveling accomplishes this by moving data that has not been modified for an extended period of time out of blocks that have seen few PROGRAM/ERASE cycles and into more heavily worn blocks. This frees up fresher blocks for new data while reducing expected wear on tired blocks. Dynamic wear leveling, by contrast, acts on in-flight data to ensure it is preferentially written to the least-worn free blocks rather than those closer to the end of their rated life. These techniques are used together within the controller to optimally balance the wear profile of the NAND array.

Firmware Update Capability

The SSD supports firmware updates as defined by the NVMe specification. When a FIRMWARE DOWNLOAD command completes, a FIRMWARE COMMIT command must be issued.

Power Loss Subsystem and Rebuild

The SSD supports an unexpected power loss with a power-backed write cache. No user data is lost during an unexpected power loss. When power is subsequently restored, the SSD returns to a ready state within a maximum of 60 seconds.

Boot

The 9200 is not intended to be a bootable device. Boot functionality is not validated by Micron, and any use in this manner is done at the user's own risk. Please visit Micron.com to find other SSD products that are recommended for boot.

SMBus Sideband Management

If the system management bus (SMBus) is configured to be enabled, the SSD uses the SMBus interface for presenting product data, monitoring drive health, checking drive status before power-up, and error posting.

Protocol supported: Enterprise SSD Form Factor interface with its accompanying vital product data (VPD) definition.

Management data and vital product data may be accessed at fixed addresses with +3.3V_{AUX} prior to powering up the drive completely. This data continues to be available at this fixed address when the drive is fully powered up.

Table 6: Out-of-Band Management Details

| Out-of-Band Protocol | SMBUS Address | Alternate Address (due to bit shift) | Data |
|-------------------------------|---------------|--------------------------------------|---------------------------------|
| Enterprise SSD Form Factor | 0x53 | 0xA6 | Vital product data (VPD) |
| NVMe Management Interface 1.0 | 0x6A | 0xD4 | Subsystem management data (SMD) |

- Notes:
1. SMBUS addresses will appear at an alternate address in certain tools due the inclusion of direction bit in the SMBUS spec.
 2. Out-of-band management is disabled by default.

Table 7: Vital Product Data (VPD) Structure

| Address | #Bytes | Function | Value | Byte Offset | Description |
|----------------|--------|----------------------------|--------|-------------|--|
| 0x53 (7bit) | 3 | Class code | 02h | 0 | Device type and programming interface |
| | | | 08h | 1 | |
| | | | 01h | 2 | |
| | 2 | ID | 44h | 3 | PCI-SIG vendor ID (0x1344 is assigned to Micron) |
| | | | 13h | 4 | |
| | | | Varies | 5–24 | Serial number |
| | | | Varies | 25–64 | Model number |
| | 1 | PCIe port0 capabilities | 03h | 65 | Maximum link speed |
| | 1 | | 04h | 66 | Maximum link width |
| | 1 | PCIe port1 capabilities | 00h | 67 | Maximum link speed |
| | 1 | | 00h | 68 | Maximum link width |
| | 1 | Initial power requirements | 08h | 69 | 12V Power rail initial power requirement (W) |
| | 2 | Reserved | 0 | 70–71 | – |
| | 1 | Maximum power requirements | 24h | 72 | 12V power rail maximum power requirement (W) |
| | 2 | Reserved | 0 | 73–74 | – |
| | 2 | Capability list pointer | 4Dh | 75 | 16b address offset pointers to start of capability list, see Capability List Pointer table |
| 00h | | | 76 | | |

Table 8: Capability List Pointer

| Address | #Bytes | Value | Byte Offset | R/W | Description |
|---------|--------|--------|-------------|-----|---|
| 0x004D | 2 | A5h | 0 | RO | PCI-SIG vendor specific capability |
| | | 00h | 1 | | |
| | 2 | 00h | 2 | RO | Pointer to next capability |
| | | 00h | 3 | | |
| | 2 | 44h | 4 | RO | PCI-SIG vendor ID (0x1344 is assigned to Micron) |
| | | 13h | 5 | | |
| | 2 | 0000h | 6–7 | RO | Reserved |
| | 2 | Varies | 8 | RO | Temperature value (Celsius), little-endian format. For example, byte[8:9] = 29h 00h indicates the temperature is 41°C |
| | | Varies | 9 | RO | |

Electrical Characteristics

Stresses greater than those listed may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

Table 9: Power Consumption

| Specification | 9200 ECO (TB) | | 9200 PRO (TB) | | | 9200 MAX (TB) | | | Unit |
|--------------------------------------|-----------------|------|---------------|------|------|---------------|-----|-----|------|
| | 8.0 | 11.0 | 1.92 | 3.84 | 7.68 | 1.6 | 3.2 | 6.4 | |
| Active reads (Maximum RMS) | 25 ² | | | | | | | | W |
| Active writes (Maximum RMS) | 25 ² | | | | | | | | |
| 128K sequential reads (Average RMS) | 19 | 21 | 17 | 19 | 19 | 17 | 19 | 19 | |
| 128K sequential writes (Average RMS) | 20 | 20 | 18 | 20 | 20 | 18 | 20 | 20 | |
| 4K random reads (Average RMS) | 17 | 17 | 16 | 16 | 17 | 16 | 16 | 17 | |
| 4K random writes (Average RMS) | 20 | 21 | 18 | 21 | 20 | 18 | 20 | 21 | |
| Mixed 70/30 read/write (Average RMS) | 19 | 20 | 17 | 20 | 18 | 16 | 20 | 17 | |

- Notes: 1. Average power consumption.
 2. 25W power limiting by VU command.

Table 10: Operating Voltage

| Electrical Characteristic | | Value |
|--------------------------------|-------------------------------|------------------|
| 12V power rail | Operating voltage | 12Vdc (±8%) |
| | MAX/MIN rise time | 10–100ms |
| | MAX/MIN fall time | <5s |
| | Inrush current (typical peak) | 3.0A |
| | MAX average current (RMS) | 2.5A |
| 3.3V _{AUX} power rail | Operating voltage | 3.3V (–8% to 8%) |
| | MAX/MIN rise time | 50ms/1ms |
| | MAX/MIN fall time | 5s/1ms |
| | MAX average current | 20mA |

Environmental Conditions

Table 11: Temperature and Airflow

| Temperature and Airflow | Specification | Notes |
|---|--|-------|
| Operating temperature (as indicated by the SMART temperature attribute) | 0°C to 85°C | 1 |
| Operating ambient temperature | Ambient: 0°C to 35°C; Case: 0°C to 70°C | 2 |
| Operating airflow | 450 LFM at 25°C ambient | 3, 4 |
| Storage temperature | -40°C to 85°C | 5 |
| Humidity | 25% to 95% noncondensing | |

- Notes:
1. If SMART temperature exceeds 75°C (SMART composite), write performance will be throttled.
 2. Temperature of air impinging on the SSD.
 3. Airflow must flow along the length of the drive parallel to and through any cooling fins.
 4. Airflow is measured upstream of the drive before any acceleration as the air goes around the drive.
 5. Contact Micron for additional information.

Table 12: Shock and Vibration

| Shock and Vibration | Specification |
|----------------------------|---|
| Shock (nonoperational) | 1500G at 0.5ms half-sine |
| Vibration (nonoperational) | 3.1 G _{RMS} 5–800Hz at 30 min/axis |

- Note:
1. Shock and vibration ratings refer to the ability to withstand stress events only. Prolonged or repeated exposure to conditions listed or greater stresses may result in permanent damage to the device. Functional operation of the device under these conditions is not implied. See warranty for more information.

Supported Commands

NVMe Admin Command Set

The 9200 supports the following mandatory NVMe admin commands, as described in the NVMe 1.2 specification:

- Delete I/O submission queue
- Create I/O submission queue
- Get log page
- Delete I/O completion queue
- Create I/O completion queue
- Identify
- Abort
- Set features
- Get features
- Asynchronous event request

The following optional NVMe admin commands are also supported:

- Firmware activate
- Firmware image download
- Format NVM
- Security Send
- Security Receive

NVMe I/O Command Set

The 9200 supports the following mandatory NVMe I/O commands, as described in the NVMe 1.2 specification:

- Write
- Read
- Flush

The following optional NVMe I/O commands are also supported:

- Dataset management
- Deallocate

Log Pages

The Get Log Page command can be used to retrieve the following logs:

- 01h - Error information
- 02h - SMART / health information
- 03h - Firmware slot information
- CAh - Vendor Unique SMART
- 05h - Command Effects Log

SMART and Health Information

The SSD supports SMART/Health log information as defined in the NVMe specification as well as extended health information. These logs persist through power cycles and reflect lifetime data.

Table 13: SMART/Health Information (Log Identifier 02h)

| Bytes | Name | Description |
|-------|---------------------------|--|
| 0 | Critical warning | <p>Indicates critical warnings for the state of the controller. Each bit corresponds to a critical warning type; multiple bits may be set. If a bit is cleared to 0, the critical warning does not apply. Critical warnings may result in an asynchronous event notification to the host.</p> <ul style="list-style-type: none"> • Bit 00: If set to 1, the available spare space has fallen below the threshold. • Bit 01: If set to 1, the temperature has exceeded a critical threshold. • Bit 02: If set to 1, the device reliability has been degraded due to significant media-related errors or any internal error that degrades device reliability. • Bit 03: If set to 1, the media has been placed in read-only mode. • Bit 04: 0, the controller does not implement a volatile memory back-up solution. • Bits 07:05 Reserved |
| 2:1 | Temperature | Contains the maximum temperature of the overall device (controller and NVM included) in units of Kelvin. If it exceeds the temperature threshold, an asynchronous event may be issued to the host. |
| 3 | Available spare | Contains a normalized percentage (0–100%) of the remaining available spare capacity, beginning at 100% and decreasing. |
| 4 | Available spare threshold | When the available spare falls below the threshold indicated in this field, an asynchronous event may be issued to the host. The value is indicated as a normalized percentage (0–100%). Threshold is set to 5%. |
| 5 | Percentage used | <p>Contains a vendor-specific estimate of the percentage of the device life used based on the actual device usage and the manufacturer's prediction of device life.</p> <p>A value of 100 indicates that the estimated endurance of the device has been consumed, but may not indicate a device failure.</p> <p>Refer to the JEDEC JESD218 standard for SSD device life and endurance measurement techniques.</p> |
| 31:6 | Reserved | Reserved |
| 47:32 | Data units read | Contains the number of 512-byte data units the host has read from the controller; this value does not include metadata. This value is reported in thousands (that is, a value of 1 corresponds to 1000 units of 512 bytes read) and is rounded up. When the LBA size is a value other than 512 bytes, the controller shall convert the amount of data read to 512-byte units. |

Table 13: SMART/Health Information (Log Identifier 02h) (Continued)

| Bytes | Name | Description |
|---------|----------------------------------|---|
| 63:48 | Data units written | Contains the number of 512-byte data units the host has written to the controller; this value does not include metadata. This value is reported in thousands (that is, a value of 1 corresponds to 1000 units of 512 bytes written) and is rounded up. When the LBA size is a value other than 512 bytes, the controller shall convert the amount of data written to 512-byte units. For the NVM command set, logical blocks written as part of write operations shall be included in this value. Write uncorrectable commands shall not impact this value. |
| 79:64 | Host read commands | Contains the number of read commands issued to the controller. |
| 95:80 | Host write commands | Contains the number of write commands issued to the controller. For the NVM command set, this is the number of write commands. |
| 111:96 | Controller busy time | Contains the amount of time the controller is busy with I/O commands. The controller is busy when there is a command outstanding to an I/O queue (specifically, a command was issued via an I/O submission queue tail doorbell write and the corresponding completion queue entry has not been posted yet to the associated I/O completion queue.) This value is reported in minutes. |
| 127:112 | Power cycles | Contains the number of power cycles. |
| 143:128 | Power on hours | Contains the number of power-on hours. This does not include time that the controller was powered and in a low-power state condition. |
| 159:144 | Unsafe shutdowns | Contains the number of unsafe shutdowns. This count is incremented when a shutdown notification (CC.SHN) is not received prior to loss of power. |
| 175:160 | Media errors | Contains the number of occurrences where the controller detected an unrecovered data integrity error. Errors such as uncorrectable ECC, CRC checksum failure, or LBA tag mismatch are included in this field. |
| 191:176 | Number of error info log entries | Contains the number of error information log entries over the life of the controller. |
| 511:192 | Reserved | Reserved |

Vendor Unique SMART

In addition to the standard SMART log, the 9200 provides the following details in a vendor unique log:

Table 14: Vendor Unique SMART Attributes (Log Identifier CAh)

| Bytes | Name | Description |
|-------|-----------------------|---|
| 0:1 | F9 - NAND_writes_1GiB | Raw value reports the number of writes to NAND in 1 GiB increments. |
| 3:4 | Normalized value | |
| 5:11 | Current raw value | |
| 12:13 | FA - NAND_reads_1GiB | Raw value reports the number of reads to NAND in 1 GiB increments. |
| 15:16 | Normalized value | |
| 17:23 | Current raw value | |

Table 14: Vendor Unique SMART Attributes (Log Identifier CAh) (Continued)

| Bytes | Name | Description |
|-------|------------------------------|--|
| 24:25 | EA - Thermal throttle status | Raw value indicates throttle status and total throttling time. |
| 27:28 | Normalized value | Byte 0: If set to 1, throttling is active; if set to 0, throttling is not active |
| 29:35 | Current raw value | Bytes 1–4: Total throttling time in minutes since power on Bytes 5: Reserved |
| 36:37 | E7 - Temperature | Raw value reports the maximum and minimum temperature in Kelvin over the lifetime of the device. |
| 39:40 | Normalized value | Byte 0–1: The maximum temperature sampled from the temperature sensor |
| 41:47 | Current raw value | Bytes 2–3: The minimum temperature sampled from the temperature sensor Bytes 4–5: The current temperature sampled from the temperature sensor |
| 48:49 | E8 - Power consumption | Raw value reports the maximum and minimum average power consumption in watts. |
| 51:52 | Normalized value | Bytes 0–1: The maximum power consumption |
| 53:59 | Current raw value | Bytes 2–3: The minimum power consumption Bytes 4–5: The average power consumption |
| 60:61 | AF - Power loss protection | Normalized value reports the power loss protection status. 100 indicates protection was successful. 0 indicates protection failed. A power loss failure indicator will persist until a Format NVM command is executed. |
| 63:64 | Normalized value | |
| 65:71 | Current raw value | |

Get/Set Features

The following features can be configured or retrieved using NVMe SET FEATURES and GET FEATURES commands:

- 02h – Power management (Commands are accepted but values are not returned. A custom power governor feature is utilized for power management.)
- 04h – Temperature threshold
- 05h – Set error recovery
- 07h – Number of queues (Maximum supported is 128 for both submission and completion queues.)
- 08h – Interrupt coalescing
- 09h – Interrupt vector configuration
- 0Bh – Asynchronous event configuration
- D4h – Device initiated thermal

Interface Connectors

The host interface connector conforms to the PCIe Electromechanical Specification.

A mechanical indent is used to separate the PCIe power pins from the differential signal contacts. The pins are numbered below in ascending order from left to right. Side B refers to component side. Side A refers to the solder side.

U.2 Pin Assignments

The U.2 2.5" form factor follows the SFF-8639 specification and supports built-in latching.

Table 15: PCIe Interface Connector Pin Assignments (U.2 Form Factor)

| Pin | Name | Description | Pin | Name | Description |
|-----|----------|--------------------------------|-----|----------|------------------|
| S1 | GND | Ground | E7 | REFCLK0+ | PCIe REFCLK 0 p |
| S2 | | DNC | E8 | REFCLK0- | PCIe REFCLK 0 p |
| S3 | | DNC | E9 | GND | Ground |
| S4 | GND | Ground | E10 | PETp0 | PCIe TX Lane 0 p |
| S5 | | DNC | E11 | PETn0 | PCIe TX Lane 0 n |
| S6 | | DNC | E12 | GND | Ground |
| S7 | GND | Ground | E13 | PERn0 | PCIe RX Lane 0 n |
| E1 | REFCLK1+ | DNC | E14 | PERp0 | PCIe RX Lane 0 p |
| E2 | REFCLK1- | DNC | E15 | GND | Ground |
| E3 | 3.3Vaux | 3.3V auxiliary power | E16 | RSVD | Reserved |
| E4 | PERST1# | DNC | S8 | GND | Ground |
| E5 | PERST0# | PCIe Fundamental Reset | S9 | | DNC |
| E6 | RSVD | Reserved | S10 | | DNC |
| P1 | | DNC | S11 | GND | Ground |
| P2 | | DNC | S12 | | DNC |
| P3 | | DNC | S13 | | DNC |
| P4 | IfDet_N | Interface detect | S14 | GND | Ground |
| P5 | GND | Ground | S15 | RSVD | Reserved |
| P6 | GND | Ground | S16 | GND | Ground |
| P7 | | DNC | S17 | PETp1 | PCIe TX Lane 1 p |
| P8 | | DNC | S18 | PETn1 | PCIe TX Lane 1 n |
| P9 | | DNC | S19 | GND | Ground |
| P10 | PRSNT_N | Presence detect | S20 | PERn1 | PCIe RX Lane 1 n |
| P11 | Activity | Activity signal from the drive | S21 | PERp1 | PCIe RX Lane 1 p |
| P12 | Hot-Plug | Ground | S22 | GND | Ground |
| P13 | +12V_pre | 12V power | S23 | PETp2 | PCIe TX Lane 2 p |
| P14 | +12V | 12V power | S24 | PETn2 | PCIe TX Lane 2 n |
| P15 | +12V | 12V power | S25 | GND | Ground |
| | | | S26 | PERn2 | PCIe RX Lane 2 n |

Table 15: PCIe Interface Connector Pin Assignments (U.2 Form Factor) (Continued)

| Pin | Name | Description | Pin | Name | Description |
|-----|------|-------------|-----|--------------|------------------|
| | | | S27 | PERp2 | PCIe RX Lane 2 p |
| | | | S28 | GND | Ground |
| | | | E17 | PETp3 | PCIe TX Lane 3 p |
| | | | E18 | PETn3 | PCIe TX Lane 3 n |
| | | | E19 | GND | Ground |
| | | | E20 | PERn3 | PCIe RX Lane 3 n |
| | | | E21 | PERp3 | PCIe RX Lane 3 p |
| | | | E22 | GND | Ground |
| | | | E23 | SMCLK | SMBus clock |
| | | | E24 | SMDAT | SMBus data |
| | | | E25 | DualPortEn_N | Dual port enable |

- Notes:
1. PRSNT_N is open and IfDet_N is grounded to indicate PCIe support.
 2. DualPortEn_N pin should be left un-connected or un-driven by the system to enable single port operation with all 4 lanes. If this pin is asserted (driven low) by the system, the SSD will function as PCIe x2 lane only.

PCIe Header

Figure 2: 9200 MAX PCIe Header



Figure 3: 9200 PRO PCIe Header

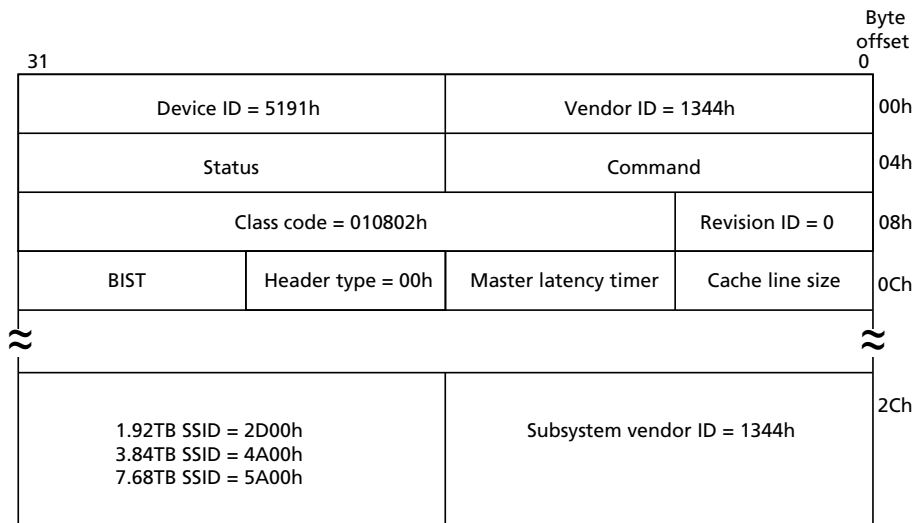


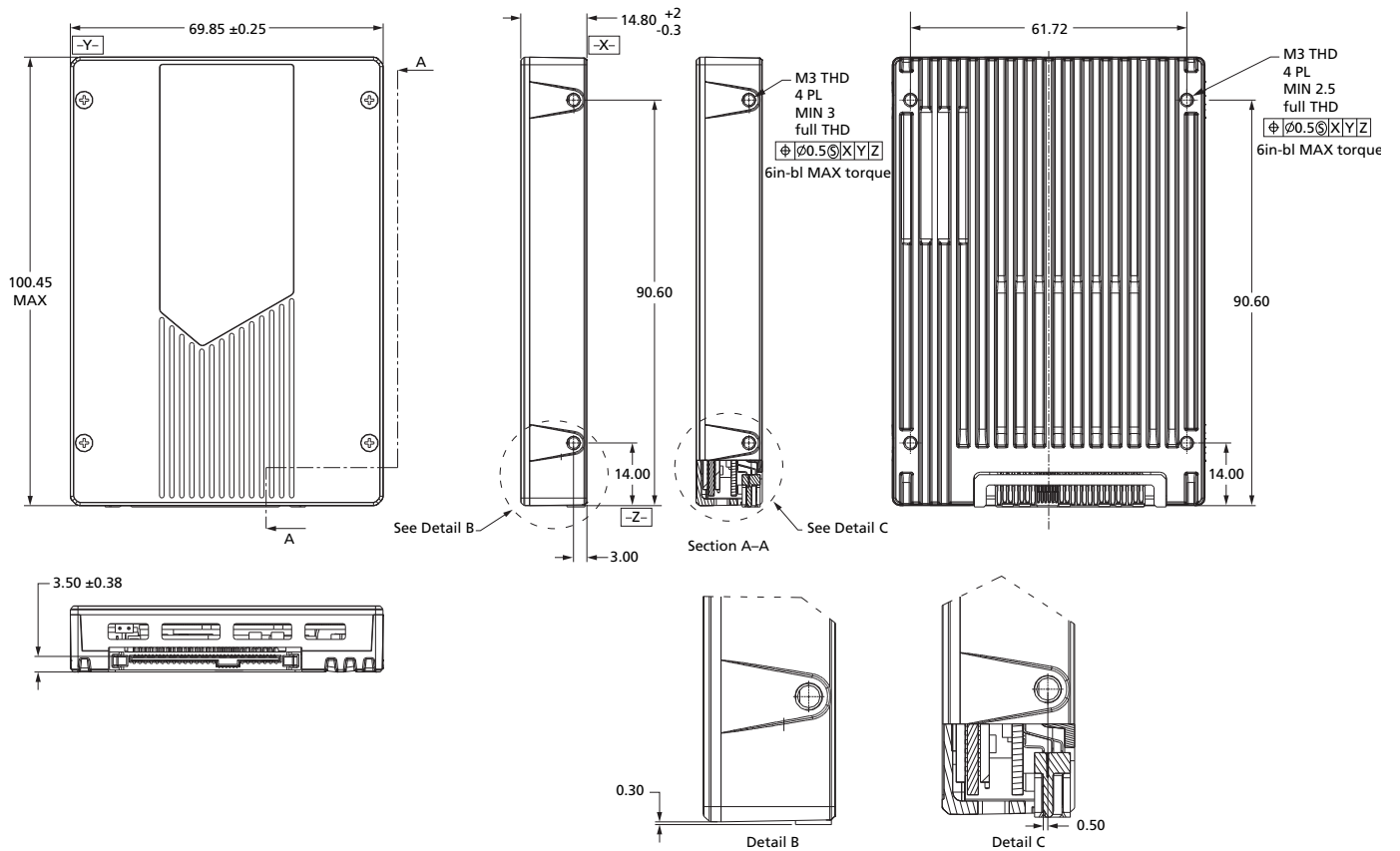
Figure 4: 9200 ECO PCIe Header



Physical Configuration

Micron's 9200 conforms to PCI Express CEM and SFF-8639 specifications.

Figure 5: U.2 (2.5") Nominal Dimensions



Note: 1. Length does not include 0.3 connector protrusion.

Compliance

The device complies with the following specifications:

- CE (Europe): EN 55022 Class B, EN 55024, RoHS
- UL: UL-60950-1, 2nd Edition
- BSMI (Taiwan): Approval to CNS 13438 Class B
- RCM (Australia, New Zealand): AS/NZS CISPR22 Class B
- KCC RRL (Korea): Approval to KN32 Class B, KN 35
- W.E.E.E.: Compliance with EU WEEE directive 2012/19/EC. Additional obligations may apply to customers who place these products in the markets where WEEE is enforced.
- TUV (Germany): Approval to IEC60950/EN60950
- V_{CCI} (Japan): 2015-04 Class B, CISPR22
- IC (Canada): ICES-003 Class B, CISPR22 Class B
- This Class B digital apparatus complies with Canadian ICES-003.
- Cet appareil numérique de la classe B est conforme à la norme NMB-003 du Canada

FCC Rules

This equipment has been tested and found to comply with the limits for a digital device, pursuant to part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) this device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and the receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

References

- PCI Express CEM Specification V2.0
- PCI Express Specification V3.0
- SFF-8639
- IDEMA Standard LBA 1-03
- Telcordia SR-322 Procedures
- NVM Express Specification Revision 1.2

Appendix A

Identify Data Structures

Table 16: Identify Controller Data Structure

| Identify Controller Data Structure Bytes | DS ¹ | Default Value | M/O ² | Feature Name | Description |
|--|-----------------|----------------|------------------|---|---|
| 1:0 | F | 0x1344 | M | PCI vendor ID (VID) | Contains the company vendor identifier that is assigned by the PCI SIG. |
| 3:2 | F | 0x1344 | M | PCI subsystem vendor ID (SSVID) | Contains the company vendor identifier that is assigned by the PCI SIG for the subsystem. |
| 23:4 | V | varies | M | Serial number (SN) | Contains the serial number for the NVM subsystem. |
| 63:24 | V | varies | M | Model number (MN) | Contains the model number for the NVM subsystem. |
| 71:64 | V | varies | M | Firmware revision (FR) | Contains the currently active firmware revision for the NVM subsystem. |
| 72 | F | 0x0 | M | Recommended arbitration burst (RAB) | This is the recommended arbitration burst size. |
| 75:73 | F | 0x75-0xA0-0x00 | M | IEEE OUI identifier (IEEE) | Contains the organization unique identifier (OUI) for the controller vendor. |
| 76 | X | 0x0 | O | Controller multi-path I/O and namespace sharing capabilities (CMIC) | This field specifies multi-path I/O and namespace sharing capabilities of the controller and NVM subsystem. |
| 77 | F | 0x20 | M | Maximum data transfer size (MDTS) | Supports MDTS of 128K. |
| 79:78 | F | 0x1 | M | Controller ID (CNTLID) | This field contains the controller ID of the controller whose status is reported in this data structure. |
| 83:80 | F | 0x00010200 | M | Version (VER) | This field indicates the version of the NVMe Express Specification 1.2 that the controller implementation supports. |
| 95:92 | V | 0x0 | M | Optional asynchronous events supported (OAES) | This field indicates the optional asynchronous events supported by the controller. |
| 239:96 | – | – | – | – | Reserved |

- Notes: 1. DS = Data structure; F = Fixed; V = Variable; X = Both
2. M/O = Mandatory/Optional

Table 17: Identify Namespace Data Structure

| Bytes | DS ¹ | Default Value | M/O ² | Feature Name | Description |
|----------------------------|-----------------|---------------|------------------|---|--|
| 512 | F | 0x66 | M | Submission queue entry size (SQES) | Required and maximum submission queue entry size is 64 bytes. |
| 513 | F | 0x44 | M | Completion queue entry size (CQES) | Required and maximum completion queue entry size is 16 bytes. |
| 515:514 | – | – | – | – | Reserved |
| 519:516 | F | 0x1 | M | Number of namespaces (NN) | Supports a single namespace. |
| 521:520 | F | 0x14 | M | Optional NVM command support (ONCS) | Supports dataset management and save field/select field optional NVMe commands. |
| 523:522 | F | 0x0 | M | Fused operation support (FUSES) | Fused commands not supported. |
| 524 | V | 0x4/0x0 | M | Format NVM attributes (FNA) | Cryptographic erase is supported as part of the secure erase functionality when the device is formatted as 4096-byte sector size only. |
| 525 | F | 0x0 | M | Volatile write cache (VWC) | Volatile write cache is not present. |
| 527:526 | F | 0x0 | M | Atomic write unit normal (AWUN) | Atomic write size for controller during normal equals to 4K bytes. |
| 529:528 | F | 0x0 | M | Atomic write unit power fail (AWUPF) | Indicates the atomic write size for the controller during a power fail condition equals 512 bytes. |
| 530 | X | 0x1 | M | NVM vendor specific command configuration (NVSCC) | All NVM vendor specific commands use the format defined by the NVMe specification. |
| 531 | – | – | – | – | Reserved |
| 533:532 | F | 0x0 | M | Atomic compare and write unit (ACWU) | Not supported. |
| 535:534 | – | – | – | – | Reserved |
| 539:536 | F | 0x0 | O | SGL support (SGLS) | Not supported. |
| 703:540 | – | – | – | – | Reserved |
| I/O command set attributes | | | | | |
| 2047:704 | – | – | – | – | Reserved |

- Notes: 1. DS = Data structure; F = Fixed; V = Variable; X = Both
2. M/O = Mandatory/Optional

Revision History

Rev. H – 7/18

- Updated case dimensions

Rev. G – 5/18

- Updated Drive Performance table
- Updated Total Bytes Written table: Added 128K Sequential Total Bytes Written
- Updated SMART/Health Information (Log Identifier 02h) table
- Updated Identify Data Structures in Appendix A

Rev. F – 1/18

- Updated Features section
- Updated Performance section

Rev. E – 10/17

- Removed HHHL through the data sheet
- Updated Drive Performance table and Latency table in Performance
- Updated Power Consumption table
- Corrected PCIe header information

Rev. D – 8/17

- Updated Drive Performance table, Latency table, and Quality of Service table in Performance section
- Updated Out of Band Management Details table in SMBus Sideband Management: Added NVMe Management Interface 1.0
- Updated Power Consumption table in Electrical Characteristics: Changed Idle power specification
- Updated Temperature and Airflow table in Environmental Conditions: Changed Operating ambient temperature specification and Operating airflow specification
- Updated Shock and Vibration table

Rev. C – 7/17

- Updated Part Number Chart
- Updated formatting

Rev. B – 1/17

- Updated figure 1
- Updated formatting

Rev. A – 10/16

- Initial release

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Although considered final, these specifications are subject to change, as further product development and data characterization some-
times occur.

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- Комплексную поставку.
- Работу по проектам и поставку образцов.
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- Защиту от снятия компонента с производства.
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